

Applicant	Kyocera
FCC ID:	V65S3015
Report #:	CT-S3015-13C-0611-R0

Exhibit 13 Appendix C: T-Coil Data Plot

Cell BC-10



Applicant	Kyocera
FCC ID:	V65S3015
Report #:	CT-S3015-13C-0611-R0

Test Laboratory: Kyocera Date: 6/28/2011

FCC S3015 TCoil CELL476

Communication System: CELL BC0&BC10, Frequency: 817.9 MHz, Duty Cycle: 1:1

Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m³ Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010 Measurement SW: DASY4, V4.7 Build 80 Postprocessing SW: SEMCAD, V1.8 Build 184

Temperature:

Room T = $21.8 + - 1 \deg C$, Liquid T = $22.0 + - 1 \deg C$

General Scans_476/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 51.4 dB ABM1 comp = -0.239 dB A/m BWC Factor = 0.155979 dB Location: 2.9, 0.4, 3.7 mm

General Scans_476/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

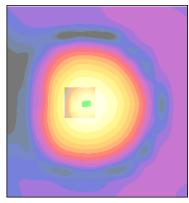
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 51.2 dB ABM1 comp = 0.063 dB A/m BWC Factor = 0.155979 dB Location: 2.2, 0.2, 3.7 mm



0 dB = 373.3



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Test Laboratory: Kyocera

FCC S3015 TCoil CELL476

Communication System: CELL BC0&BC10, Frequency: 817.9 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³ Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010 Measurement SW: DASY4, V4.7 Build 80 Postprocessing SW: SEMCAD, V1.8 Build 184

Temperature:

Room T = $21.8 + - 1 \deg C$, Liquid T = $22.0 + - 1 \deg C$

General Scans 476/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 44.4 dB ABM1 comp = -9.39 dB A/m BWC Factor = 0.155979 dB Location: -9.2, 0.8, 3.7 mm

General Scans_476/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

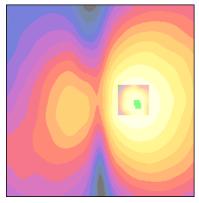
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 44.4 dB ABM1 comp = -9.69 dB A/m BWC Factor = 0.155979 dB Location: -9.5, 1.6, 3.7 mm



0 dB = 165.7



Applicant	Kyocera
FCC ID:	V65S3015
Report #:	CT-S3015-13C-0611-R0

Test Laboratory: Kyocera

FCC_S3015_TCoil_CELL476

Communication System: CELL BC0&BC10, Frequency: 817.9 MHz, Duty Cycle: 1:1

Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³ Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010 Measurement SW: DASY4, V4.7 Build 80 Postprocessing SW: SEMCAD, V1.8 Build 184

Temperature:

Room T = $21.8 + - 1 \deg C$, Liquid T = $22.0 + - 1 \deg C$

General Scans_476/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 48.7 dB ABM1 comp = -7.93 dB A/m BWC Factor = 0.155979 dB Location: 0.8, -5.4, 3.7 mm

General Scans_476/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

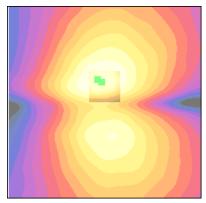
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 49.3 dB ABM1 comp = -7.42 dB A/m BWC Factor = 0.155979 dB Location: 1.8, -6, 3.7 mm



0 dB = 273.4



Applicant	Kyocera
FCC ID:	V65S3015
Report #:	CT-S3015-13C-0611-R0

Test Laboratory: Kyocera

FCC_S3015_TCoil_CELL580

Communication System: CDMA_Tri_BC0&10, Frequency: 820.5 MHz, Duty Cycle: 1:1

Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m³ Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn603, Calibrated: 9/20/2010 Measurement SW: DASY4, V4.7 Build 80 Postprocessing SW: SEMCAD, V1.8 Build 184

Temperature:

Room T = $21.8 + - 1 \deg C$, Liquid T = $22.0 + - 1 \deg C$

General Scans_580/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 51.0 dB ABM1 comp = -0.476 dB A/m BWC Factor = 0.155041 dB Location: 2.9, 0.4, 3.7 mm

General Scans_580/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

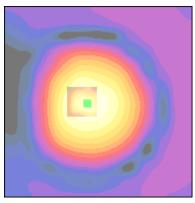
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 51.2 dB ABM1 comp = -0.109 dB A/m BWC Factor = 0.155041 dB Location: 2.6, 0.6, 3.7 mm



0 dB = 352.8



Applicant	Kyocera
FCC ID:	V65S3015
Report #:	CT-S3015-13C-0611-R0

Test Laboratory: Kyocera

FCC_S3015_TCoil_CELL580

Communication System: CDMA_Tri_BC0&10, Frequency: 820.5 MHz, Duty Cycle: 1:1

Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m³ Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn603, Calibrated: 9/20/2010 Measurement SW: DASY4, V4.7 Build 80 Postprocessing SW: SEMCAD, V1.8 Build 184

Temperature:

Room T = $21.8 + - 1 \deg C$, Liquid T = $22.0 + - 1 \deg C$

General Scans 580/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 51.0 dB ABM1 comp = -0.476 dB A/m BWC Factor = 0.155041 dB Location: 2.9, 0.4, 3.7 mm

General Scans_580/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

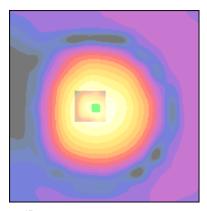
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 51.2 dB ABM1 comp = -0.109 dB A/m BWC Factor = 0.155041 dB Location: 2.6, 0.6, 3.7 mm



0 dB = 352.8



Applicant	Kyocera
FCC ID:	V65S3015
Report #:	CT-S3015-13C-0611-R0

Test Laboratory: Kyocera

FCC_S3015_TCoil_CELL580

Communication System: CDMA_Tri_BC0&10, Frequency: 820.5 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m³ Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn603, Calibrated: 9/20/2010 Measurement SW: DASY4, V4.7 Build 80 Postprocessing SW: SEMCAD, V1.8 Build 184

Temperature:

Room T = $21.8 + - 1 \deg C$, Liquid T = $22.0 + - 1 \deg C$

General Scans_580/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 44.1 dB ABM1 comp = -9.32 dB A/m BWC Factor = 0.155041 dB Location: -8.7, 1.2, 3.7 mm

General Scans_580/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

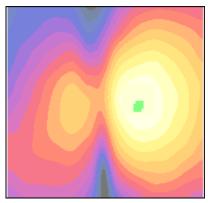
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 44.2 dB ABM1 comp = -9.11 dB A/m BWC Factor = 0.155041 dB Location: -8.3, 2, 3.7 mm



0 dB = 159.9



Applicant	Kyocera
FCC ID:	V65S3015
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Test Laboratory: Kyocera

FCC_S3015_TCoil_CELL580

Communication System: CDMA_Tri_BC0&10, Frequency: 820.5 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m³ Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn603, Calibrated: 9/20/2010 Measurement SW: DASY4, V4.7 Build 80 Postprocessing SW: SEMCAD, V1.8 Build 184

Temperature:

Room T = $21.8 + - 1 \deg C$, Liquid T = $22.0 + - 1 \deg C$

General Scans 580/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 48.6 dB ABM1 comp = -8.38 dB A/m BWC Factor = 0.155041 dB Location: 0.4, -5, 3.7 mm

General Scans_580/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

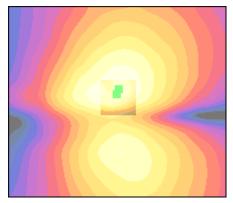
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 48.6 dB ABM1 comp = -8.53 dB A/m BWC Factor = 0.155041 dB Location: -0.2, -6.2, 3.7 mm



0 dB = 269.6



Applicant	Kyocera
FCC ID:	V65S3015
Report #:	CT-S3015-13C-0611-R0

Test Laboratory: Kyocera

FCC_S3015_TCoil_CELL684

Communication System: CDMA_Tri_BC0&10, Frequency: 823.1 MHz, Duty Cycle: 1:1

Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m³ Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn603, Calibrated: 9/20/2010 Measurement SW: DASY4, V4.7 Build 80 Postprocessing SW: SEMCAD, V1.8 Build 184

Temperature:

Room T = $21.8 + - 1 \deg C$, Liquid T = $22.0 + - 1 \deg C$

General Scans_684/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 51.2 dB ABM1 comp = -0.448 dB A/m BWC Factor = 0.155041 dB Location: 3.3, 0, 3.7 mm

General Scans_684/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

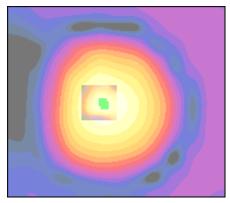
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 51.2 dB ABM1 comp = -0.305 dB A/m BWC Factor = 0.155041 dB Location: 3, 0.6, 3.7 mm



0 dB = 362.1



Applicant	Kyocera
FCC ID:	V65S3015
Report #:	CT-S3015-13C-0611-R0

Test Laboratory: Kyocera

FCC_S3015_TCoil_CELL684

Communication System: CDMA_Tri_BC0&10, Frequency: 823.1 MHz, Duty Cycle: 1:1

Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m³ Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn603, Calibrated: 9/20/2010 Measurement SW: DASY4, V4.7 Build 80 Postprocessing SW: SEMCAD, V1.8 Build 184

Temperature:

Room T = 21.8 + - 1 deg C, Liquid T = 22.0 + - 1 deg C

General Scans_684/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 44.0 dB ABM1 comp = -9.42 dB A/m BWC Factor = 0.155041 dB Location: -8.7, 0.8, 3.7 mm

General Scans_684/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

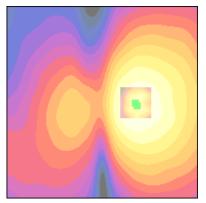
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 44.4 dB ABM1 comp = -8.97 dB A/m BWC Factor = 0.155041 dB Location: -8.3, 0, 3.7 mm



0 dB = 158.9



Applicant	Kyocera
FCC ID:	V65S3015
Report #:	CT-S3015-13C-0611-R0

Test Laboratory: Kyocera

FCC_S3015_TCoil_CELL684

Communication System: CDMA_Tri_BC0&10, Frequency: 823.1 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m³ Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn603, Calibrated: 9/20/2010 Measurement SW: DASY4, V4.7 Build 80 Postprocessing SW: SEMCAD, V1.8 Build 184

Temperature:

Room T = $21.8 + - 1 \deg C$, Liquid T = $22.0 + - 1 \deg C$

General Scans 684/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 48.7 dB ABM1 comp = -8.17 dB A/m BWC Factor = 0.155041 dB Location: 1.7, -5.4, 3.7 mm

General Scans_684/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

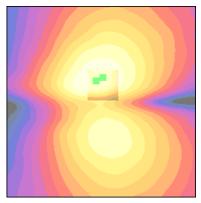
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 48.9 dB ABM1 comp = -8.23 dB A/m BWC Factor = 0.155041 dB Location: 0, -6.2, 3.7 mm



0 dB = 271.5



Applicant	Kyocera
FCC ID:	V65S3015
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Cell BC-0



Applicant	Kyocera
FCC ID:	V65S3015
Report #:	CT-S3015-13C-0611-R0

Test Laboratory: Kyocera

FCC_S3015_TCoil_CELL1013

Communication System: CDMA_Tri_BC0&10, Frequency: 824.7 MHz, Duty Cycle: 1:1

Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m³ Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn603, Calibrated: 9/20/2010 Measurement SW: DASY4, V4.7 Build 80 Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature: Room T = 21.8 + - 1 deg C, Liquid T = 22.0 + - 1 deg C

General Scans_1013/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 51.0 dB ABM1 comp = -0.985 dB A/m BWC Factor = 0.155041 dB Location: 3.8, 0.4, 3.7 mm

General Scans_1013/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

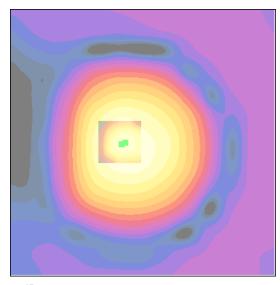
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 51.2 dB ABM1 comp = -0.469 dB A/m BWC Factor = 0.155041 dB Location: 3.2, 0.2, 3.7 mm



0 dB = 352.9



Applicant	Kyocera
FCC ID:	V65S3015
Report #:	CT-S3015-13C-0611-R0

Test Laboratory: Kyocera

FCC_S3015_TCoil_CELL1013

Communication System: CDMA_Tri_BC0&10, Frequency: 824.7 MHz, Duty Cycle: 1:1

Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m³ Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn603, Calibrated: 9/20/2010 Measurement SW: DASY4, V4.7 Build 80 Postprocessing SW: SEMCAD, V1.8 Build 184

Temperature:

Room T = $21.8 + - 1 \deg C$, Liquid T = $22.0 + - 1 \deg C$

General Scans_1013/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 43.6 dB ABM1 comp = -11.2 dB A/m BWC Factor = 0.155041 dB Location: -10.4, 3.3, 3.7 mm

General Scans_1013/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

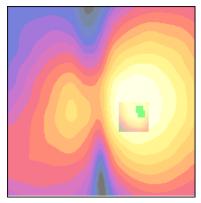
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 44.3 dB ABM1 comp = -10.1 dB A/m BWC Factor = 0.155041 dB Location: -9.9, 2.2, 3.7 mm



0 dB = 151.5



Applicant	Kyocera
FCC ID:	V65S3015
Report #:	CT-S3015-13C-0611-R0

Test Laboratory: Kyocera

FCC_S3015_TCoil_CELL1013

Communication System: CDMA_Tri_BC0&10, Frequency: 824.7 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m³ Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn603, Calibrated: 9/20/2010 Measurement SW: DASY4, V4.7 Build 80 Postprocessing SW: SEMCAD, V1.8 Build 184

Temperature:

Room T = $21.8 + - 1 \deg C$, Liquid T = $22.0 + - 1 \deg C$

General Scans_1013/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 48.7 dB ABM1 comp = -7.97 dB A/m BWC Factor = 0.155041 dB Location: 2.1, -5, 3.7 mm

General Scans_1013/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

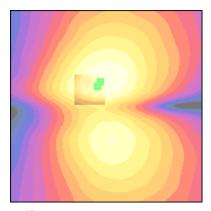
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 48.8 dB ABM1 comp = -7.83 dB A/m BWC Factor = 0.155041 dB Location: 1.4, -6.2, 3.7 mm



0 dB = 273.3



Applicant	Kyocera
FCC ID:	V65S3015
Report #:	CT-S3015-13C-0611-R0

Test Laboratory: Kyocera

FCC_S3015_TCoil_CELL384

Communication System: CELL 384BC0&BC10, Frequency: 836.52 MHz, Duty Cycle: 1:1

Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m³ Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010 Measurement SW: DASY4, V4.7 Build 80 Postprocessing SW: SEMCAD, V1.8 Build 184

Temperature:

Room T = $21.8 + - 1 \deg C$, Liquid T = $22.0 + - 1 \deg C$

General Scans_384/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 51.1 dB ABM1 comp = -0.591 dB A/m BWC Factor = 0.155979 dB Location: 3.3, 0.4, 3.7 mm

General Scans_384/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

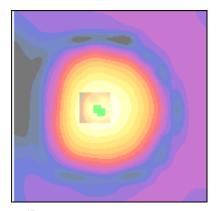
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 51.3 dB ABM1 comp = 0.090 dB A/m BWC Factor = 0.155979 dB Location: 2.4, 1.2, 3.7 mm



0 dB = 360.4



Applicant	Kyocera
FCC ID:	V65S3015
Report #:	CT-S3015-13C-0611-R0

Test Laboratory: Kyocera

FCC_S3015_TCoil_CELL384

Communication System: CELL BC0&BC10, Frequency: 836.52 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³ Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010 Measurement SW: DASY4, V4.7 Build 80 Postprocessing SW: SEMCAD, V1.8 Build 184

Temperature:

Room T = $21.8 + - 1 \deg C$, Liquid T = $22.0 + - 1 \deg C$

General Scans_384/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 44.6 dB ABM1 comp = -9.44 dB A/m BWC Factor = 0.155979 dB Location: -8.7, 0, 3.7 mm

General Scans_384/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

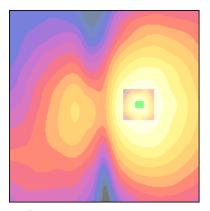
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 44.7 dB ABM1 comp = -9.03 dB A/m BWC Factor = 0.155979 dB Location: -8.3, 0, 3.7 mm



0 dB = 169.6



Applicant	Kyocera
FCC ID:	V65S3015
Report #:	CT-S3015-13C-0611-R0

Test Laboratory: Kyocera

FCC_S3015_TCoil_CELL384

Communication System: CELL BC0&BC10, Frequency: 836.52 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³ Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010 Measurement SW: DASY4, V4.7 Build 80 Postprocessing SW: SEMCAD, V1.8 Build 184

Temperature:

Room T = $21.8 + - 1 \deg C$, Liquid T = $22.0 + - 1 \deg C$

General Scans 384/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 48.6 dB ABM1 comp = -7.83 dB A/m BWC Factor = 0.155979 dB Location: 1.7, -5.8, 3.7 mm

General Scans_384/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

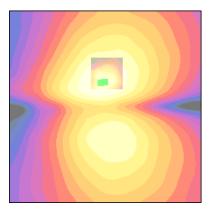
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 48.6 dB ABM1 comp = -8.01 dB A/m BWC Factor = 0.155979 dB Location: 0.6, -6.1, 3.7 mm



0 dB = 268.1



Applicant	Kyocera
FCC ID:	V65S3015
Report #:	CT-S3015-13C-0611-R0

Test Laboratory: Kyocera

FCC_S3015_TCoil_CELL777

Communication System: CELL BC0&BC10, Frequency: 848.31 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m³ Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010 Measurement SW: DASY4, V4.7 Build 80 Postprocessing SW: SEMCAD, V1.8 Build 184

Temperature:

Room T = $21.8 + - 1 \deg C$, Liquid T = $22.0 + - 1 \deg C$

General Scans_777/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 50.9 dB ABM1 comp = -0.497 dB A/m BWC Factor = 0.155979 dB Location: 3.3, 0, 3.7 mm

General Scans_777/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

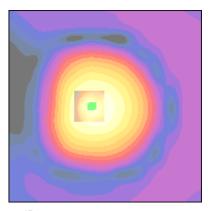
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 50.8 dB ABM1 comp = -0.565 dB A/m BWC Factor = 0.155979 dB Location: 3.8, 0.2, 3.7 mm



0 dB = 351.0



Applicant	Kyocera
FCC ID:	V65S3015
Report #:	CT-S3015-13C-0611-R0

Test Laboratory: Kyocera

FCC_S3015_TCoil_CELL777

Communication System: CELL BC0&BC10, Frequency: 848.31 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³ Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010 Measurement SW: DASY4, V4.7 Build 80 Postprocessing SW: SEMCAD, V1.8 Build 184

Temperature:

Room T = $21.8 + - 1 \deg C$, Liquid T = $22.0 + - 1 \deg C$

General Scans 777/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 44.1 dB ABM1 comp = -9.51 dB A/m BWC Factor = 0.155979 dB Location: -8.7, 0.4, 3.7 mm

General Scans_777/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

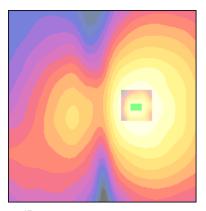
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 44.2 dB ABM1 comp = -8.82 dB A/m BWC Factor = 0.155979 dB Location: -7.7, 0.4, 3.7 mm



0 dB = 160.4



Applicant	Kyocera
FCC ID:	V65S3015
Report #:	CT-S3015-13C-0611-R0

Test Laboratory: Kyocera

FCC_S3015_TCoil_CELL777

Communication System: CELL BC0&BC10, Frequency: 848.31 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³ Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010 Measurement SW: DASY4, V4.7 Build 80 Postprocessing SW: SEMCAD, V1.8 Build 184

Temperature:

Room T = $21.8 + - 1 \deg C$, Liquid T = $22.0 + - 1 \deg C$

General Scans_777/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 48.7 dB ABM1 comp = -7.88 dB A/m BWC Factor = 0.155979 dB Location: 2.1, -5.4, 3.7 mm

General Scans_777/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

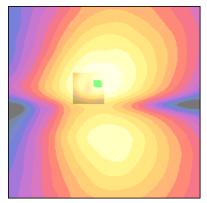
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 48.7 dB ABM1 comp = -7.94 dB A/m BWC Factor = 0.155979 dB Location: 1.6, -5.2, 3.7 mm



0 dB = 273.1



Applicant	Kyocera
FCC ID:	V65S3015
Report #:	CT-S3015-13C-0611-R0

PCS



Applicant	Kyocera
FCC ID:	V65S3015
Report #:	CT-S3015-13C-0611-R0

Test Laboratory: Kyocera

FCC S3015 TCoil PCS 25

Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1 Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ϵ_r = 1; ρ = 0 kg/m³ Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/22/2009

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010 Measurement SW: DASY4, V4.7 Build 80 Postprocessing SW: SEMCAD, V1.8 Build 184

Temperature:

Room T = $21.8 + - 1 \deg C$, Liquid T = $22.0 + - 1 \deg C$

General Scans_25/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 50.6 dB ABM1 comp = -0.681 dB A/m BWC Factor = 0.155979 dB Location: 2.9, 0.4, 3.7 mm

General Scans_25/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

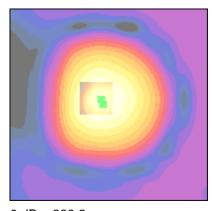
Signal Type: Audio File (.wav) 48k voice 1kHz 1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 50.7 dB ABM1 comp = -0.293 dB A/m BWC Factor = 0.155979 dB Location: 2.4, 1.4, 3.7 mm



0 dB = 338.2



Applicant	Kyocera
FCC ID:	V65S3015
Report #:	CT-S3015-13C-0611-R0

Test Laboratory: Kyocera

FCC S3015 TCoil PCS 25

Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1 Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ϵ_r = 1; ρ = 0 kg/m³ Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/22/2009

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010 Measurement SW: DASY4, V4.7 Build 80 Postprocessing SW: SEMCAD, V1.8 Build 184

Temperature:

Room T = 21.8 + - 1 deg C, Liquid T = 22.0 + - 1 deg C

General Scans_25/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 44.4 dB ABM1 comp = -9.03 dB A/m BWC Factor = 0.155979 dB Location: -8.3, 0.4, 3.7 mm

General Scans_25/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

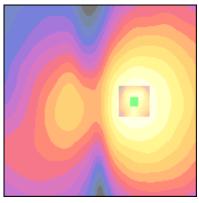
Signal Type: Audio File (.wav) 48k voice 1kHz 1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 44.0 dB ABM1 comp = -9.23 dB A/m BWC Factor = 0.155979 dB Location: -8.3, 0, 3.7 mm



0 dB = 165.2



Applicant	Kyocera
FCC ID:	V65S3015
Report #:	CT-S3015-13C-0611-R0

Test Laboratory: Kyocera

FCC S3015 TCoil PCS 25

Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1 Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ϵ_r = 1; ρ = 0 kg/m³ Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/22/2009

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010 Measurement SW: DASY4, V4.7 Build 80 Postprocessing SW: SEMCAD, V1.8 Build 184

Temperature:

Room T = $21.8 + - 1 \deg C$, Liquid T = $22.0 + - 1 \deg C$

General Scans 25/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 48.3 dB ABM1 comp = -8.14 dB A/m BWC Factor = 0.155979 dB Location: 2.1, -4.6, 3.7 mm

General Scans_25/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

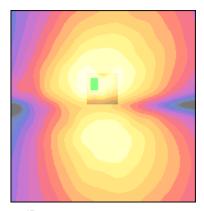
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 48.7 dB ABM1 comp = -7.81 dB A/m BWC Factor = 0.155979 dB Location: 2, -6, 3.7 mm



0 dB = 261.2



Applicant	Kyocera
FCC ID:	V65S3015
Report #:	CT-S3015-13C-0611-R0

Test Laboratory: Kyocera

FCC S3015 TCoil PCS 600

Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1 Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³ Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/22/2009

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010 Measurement SW: DASY4, V4.7 Build 80 Postprocessing SW: SEMCAD, V1.8 Build 184

Temperature:

Room T = $21.8 + - 1 \deg C$, Liquid T = $22.0 + - 1 \deg C$

General Scans_600/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 50.3 dB ABM1 comp = -0.908 dB A/m BWC Factor = 0.155979 dB Location: 3.3, 0.4, 3.7 mm

General Scans_600/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

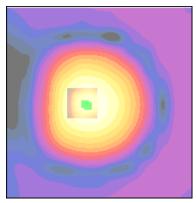
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 50.3 dB ABM1 comp = -0.273 dB A/m BWC Factor = 0.155979 dB Location: 2.6, 0.8, 3.7 mm



0 dB = 328.3



Applicant	Kyocera
FCC ID:	V65S3015
Report #:	CT-S3015-13C-0611-R0

Test Laboratory: Kyocera

FCC S3015 TCoil PCS 600

Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1 Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³ Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/22/2009

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010 Measurement SW: DASY4, V4.7 Build 80 Postprocessing SW: SEMCAD, V1.8 Build 184

Temperature:

Room T = $21.8 + - 1 \deg C$, Liquid T = $22.0 + - 1 \deg C$

General Scans_600/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 43.6 dB ABM1 comp = -9.67 dB A/m BWC Factor = 0.155979 dB Location: -8.3, 0.8, 3.7 mm

General Scans_600/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

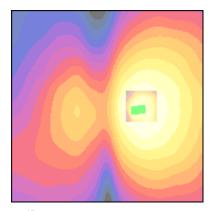
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 43.7 dB ABM1 comp = -8.47 dB A/m BWC Factor = 0.155979 dB Location: -6.7, 1, 3.7 mm



0 dB = 151.3



Applicant	Kyocera
FCC ID:	V65S3015
Report #:	CT-S3015-13C-0611-R0

Test Laboratory: Kyocera

FCC S3015 TCoil PCS 600

Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1 Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³ Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/22/2009

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010 Measurement SW: DASY4, V4.7 Build 80 Postprocessing SW: SEMCAD, V1.8 Build 184

Temperature:

Room T = $21.8 + - 1 \deg C$, Liquid T = $22.0 + - 1 \deg C$

General Scans_600/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 48.3 dB ABM1 comp = -8.10 dB A/m BWC Factor = 0.155979 dB Location: 1.7, -5.4, 3.7 mm

General Scans_600/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

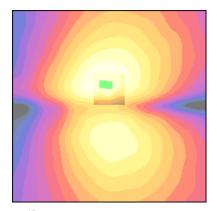
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 48.6 dB ABM1 comp = -8.24 dB A/m BWC Factor = 0.155979 dB Location: 0.2, -5.2, 3.7 mm



0 dB = 259.2



Applicant	Kyocera
FCC ID:	V65S3015
Report #:	CT-S3015-13C-0611-R0

Test Laboratory: Kyocera

FCC_S3015_TCoil_PCS 1175

Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1 Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ϵ_r = 1; ρ = 0 kg/m³ Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/22/2009

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010 Measurement SW: DASY4, V4.7 Build 80 Postprocessing SW: SEMCAD, V1.8 Build 184

Temperature:

Room T = $21.8 + - 1 \deg C$, Liquid T = $22.0 + - 1 \deg C$

General Scans_1175/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 50.3 dB ABM1 comp = -0.214 dB A/m BWC Factor = 0.155979 dB Location: 2.5, 0.4, 3.7 mm

General Scans_1175/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

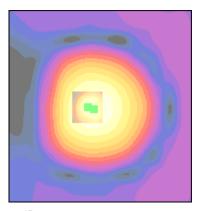
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 50.4 dB ABM1 comp = -0.694 dB A/m BWC Factor = 0.155979 dB Location: 4, 0, 3.7 mm



0 dB = 329.2



Applicant	Kyocera
FCC ID:	V65S3015
Report #:	CT-S3015-13C-0611-R0

Test Laboratory: Kyocera

FCC S3015 TCoil PCS 1175

Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1 Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ϵ_r = 1; ρ = 0 kg/m³ Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/22/2009

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010 Measurement SW: DASY4, V4.7 Build 80 Postprocessing SW: SEMCAD, V1.8 Build 184

Temperature:

Room T = 21.8 + - 1 deg C, Liquid T = 22.0 + - 1 deg C

General Scans_1175/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 43.5 dB ABM1 comp = -9.71 dB A/m BWC Factor = 0.155979 dB Location: -8.7, 0.8, 3.7 mm

General Scans_1175/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

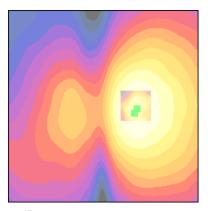
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 43.7 dB ABM1 comp = -9.31 dB A/m BWC Factor = 0.155979 dB Location: -8.1, 1.8, 3.7 mm



0 dB = 150.0



Applicant	Kyocera
FCC ID:	V65S3015
Report #:	CT-S3015-13C-0611-R0

Test Laboratory: Kyocera

FCC S3015 TCoil PCS 1175

Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1 Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ϵ_r = 1; ρ = 0 kg/m³ Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/22/2009

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010 Measurement SW: DASY4, V4.7 Build 80 Postprocessing SW: SEMCAD, V1.8 Build 184

Temperature:

Room T = $21.8 + - 1 \deg C$, Liquid T = $22.0 + - 1 \deg C$

General Scans_1175/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 48.0 dB ABM1 comp = -8.16 dB A/m BWC Factor = 0.155979 dB Location: 2.9, -5.4, 3.7 mm

General Scans_1175/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

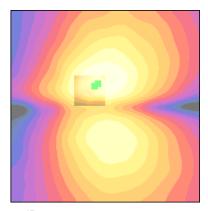
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 49.0 dB ABM1 comp = -7.59 dB A/m BWC Factor = 0.155979 dB Location: 2, -6, 3.7 mm



0 dB = 252.5